

APPLICATION NOTE MP230FC

EVALUATION KIT

EK52 is an easy to use engineering platform for prototype evaluation. The PC board is also a good starting point for an application specific layout. Provided items include: PC board, heatsink rated at 0.5°C/W, cage jacks, ceramic bypass capacitors, electrolytic bypass capacitors, three values of current limit resistors with heatsink, a high current I/O screw connection terminal strip, and spacers. The amplifier is sold separately. Common hardware such as screws, nuts and user's preference for low current I/O connectors are not provided. A manufacturer and distributor are given for source degeneration resistors (value determined by the specific application) which are not supplied.

HEATSINK

The HS26 heatsink is mechanically compatible with this amplifier. Thermal rating with optimum mounting in free air is 0.5°C/W. Forced air at 150LFPM will reduce thermal resistance to 0.37°C/W. Forced air at 500LFPM will reduce thermal resistance to 0.2°C/W.

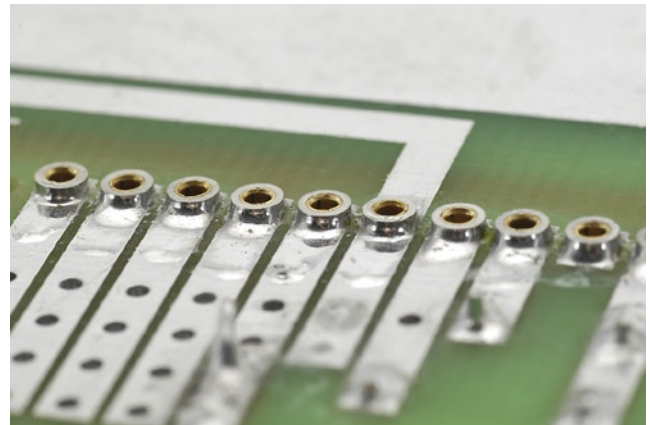


HS26 0.5°C/W

CAGE JACKS



MS11



Part number MS11 consists of a carrier strip of 30 cage jacks. The strip can easily be cut to any desired number of cage jacks. These are mounted directly in a print circuit board. After soldering, the carrier is pulled off the cage jacks. Use a spacer between the PCB and the heatsink to avoid short circuits.

THERMAL INTERFACE

Apply a thin even layer of thermal grease to the amplifier. A straight edge is useful here. Place amplifier on the heatsink and with thumbs apply pressure while moving in a circular motion to insure a void free interface. Insert fasteners and torque lightly.